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**Epitaxial oxide heterostructures on silicon** AGHAM POSADAS, J.W. REINER, F.J. WALKER, C.H. AHN, Yale University — Silicon-based MOS-FETs will soon be limited by the large off- state leakage current due to tunneling through the 1 nm thick silicon oxynitride gate dielectric layer. One solution is to replace the silicon oxynitride with a high dielectric constant material, such as  $\text{LaAlO}_3$ , which has a relatively large dielectric constant of  $\sim 24$  and band gap of 5.6 eV. We have recently grown  $\text{LaAlO}_3$  epitaxially onto silicon via a transition layer consisting of  $\text{SrTiO}_3$ . The thickness of this  $\text{SrTiO}_3$  layer is kept between 2 and 5 unit cells because of considerations of epitaxial strain and the atomic-scale interactions between the perovskite structure and the silicon substrate. The oxide heterostructures show atomically abrupt interfaces and dielectric constants close to the bulk value of  $\text{LaAlO}_3$ . Frequency and voltage dependent measurements of the complex impedance of the as-grown oxide heterostructures show a pinned Fermi level and a high density of interface states. Annealing at low temperatures in wet oxygen shows that the Fermi level can be unpinned, with a greatly reduced density of interface states.

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